Preferred Device

Silicon Hot-Carrier Diodes

Schottky Barrier Diode

These devices are designed primarily for high–efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low–cost, high–volume consumer and industrial/commercial requirements. They are available in a Surface Mount package.

- Extremely Low Minority Carrier Lifetime 15 ps (Typ)
- Very Low Capacitance 1.5 pF (Max) @ $V_R = 15 V$
- Low Reverse Leakage $-I_R = 13 \text{ nAdc}$ (Typ)
- Device Marking: 4T



ON Semiconductor Formerly a Division of Motorola

http://onsemi.com

30 VOLTS SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES



PLASTIC SOD-323 CASE 477

Junction and Storage

Temperature Range

		,	
Symbol	Rating	Value	Unit
VR	Reverse Voltage	30	Volts
THERMA	L CHARACTERISTICS		
Symbol	Characteristic	Max	Unit
PD	Total Device Dissipation FR–5 Board,* T _A = 25°C Derate above 25°C	200 1.57	mW mW/°C
R _{0JA}	Thermal Resistance Junction to Ambient	635	°C/W

*FR–5 Minimum Pad

TJ, Tstg

1 O 2 CATHODE ANODE

ORDERING INFORMATION

Device	Package	Shipping
MMDL301T1	SOD-323	3000 / Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

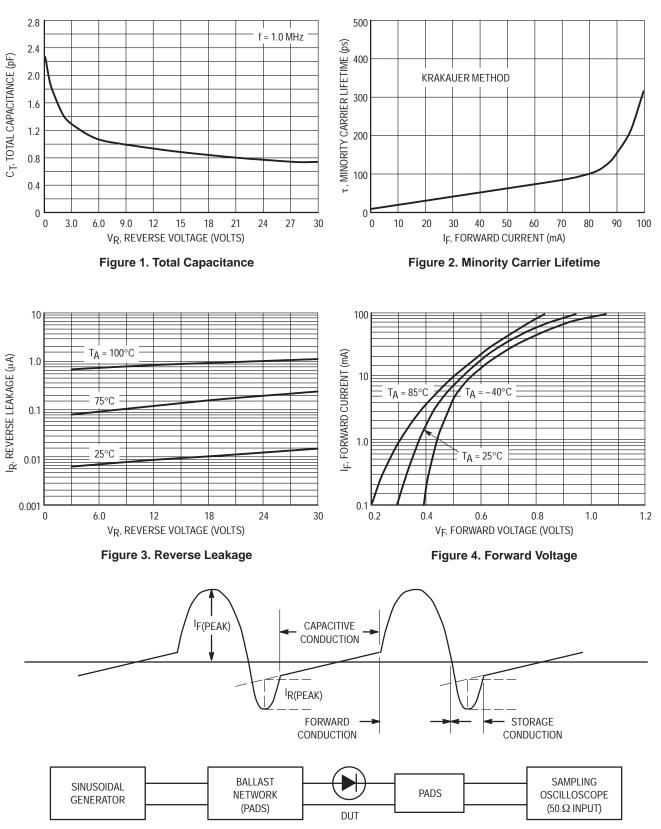
–55 to

+150

°C

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

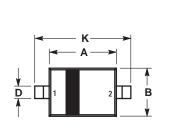
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _(BR) R	30	—	_	Volts
Total Capacitance (V_R = 15 V, f = 1.0 MHz) Figure 1	CT	—	0.9	1.5	pF
Reverse Leakage (V _R = 25 V) Figure 3	IR	—	13	200	nAdc
Forward Voltage (I _F = 1.0 mAdc) Figure 4	٧ _F	—	0.38	0.45	Vdc
Forward Voltage (I _F = 10 mAdc) Figure 4	٧ _F	_	0.52	0.6	Vdc

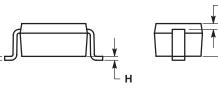


TYPICAL ELECTRICAL CHARACTERISTICS



PACKAGE DIMENSIONS





SOD-323 PLASTIC PACKAGE CASE 477-02 ISSUE A

NOTES:

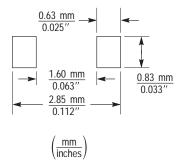
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 CONTROLLING DIMENSION: MILLIMETERS.
LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.60	1.80	0.063	0.071
В	1.15	1.35	0.045	0.053
С	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
Е	0.15 REF		0.006 REF	
Н	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
К	2.30	2.70	0.091	0.106

STYLE 1: PIN 1. CATHODE

2. ANODE



SOD-323

Soldering Footprint

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